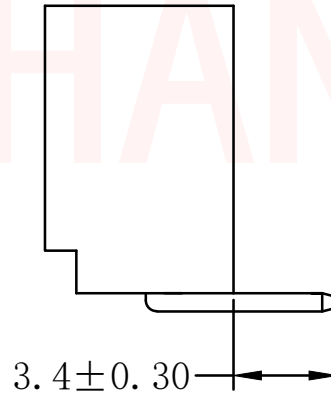
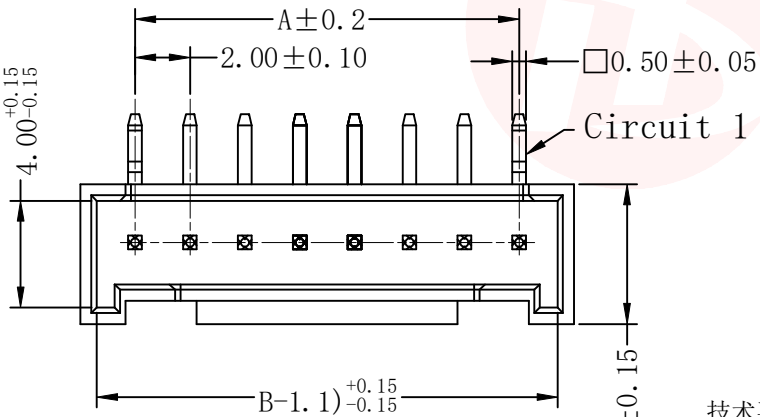
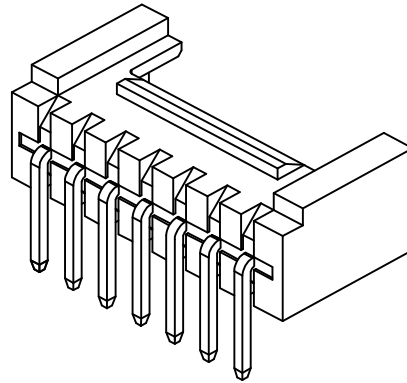
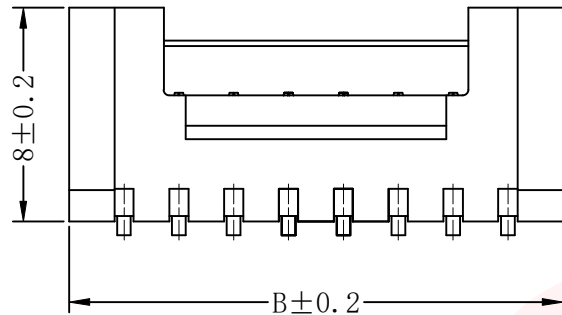




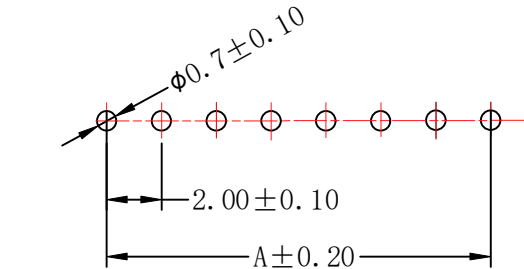
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



- 技术要求:
- 1、塑件材料: LCP/PA66 (UL-94V-0)
 - 2、接触件: 黄铜镀锡
 - 3、接触电阻: $\leq 10m\Omega$
 - 4、绝缘电阻: $\geq 1000M\Omega$
 - 5、额定电压: 250V AC DC
 - 6、额定电流: 2.0A AC DC
 - 7、耐压: 能承受1000V AC/Minute
 - 8、工作温度: $-25^{\circ} \sim +85^{\circ}$
 - 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 220^{+5}_{-0} , 时间 2.5 ± 0.5 秒
 - 10、铅和镉等六大有害物质含量要符合环保要求

TABLE:

CSG PART NO.	Dimension mm			
	PIN	A	B	C
WAFER-HY200WZ-2A	2P	2.00	6.00	2.50
WAFER-HY200WZ-3A	3P	4.00	8.00	2.50
WAFER-HY200WZ-4A	4P	6.00	10.00	3.50
WAFER-HY200WZ-5A	5P	8.00	12.00	5.50
WAFER-HY200WZ-6A	6P	10.00	14.00	7.50
WAFER-HY200WZ-7A	7P	12.00	16.00	9.50
WAFER-HY200WZ-8A	8P	14.00	18.00	11.50
WAFER-HY200WZ-9A	9P	16.00	20.00	13.50
WAFER-HY200WZ-10A	10P	18.00	22.00	15.50
WAFER-HY200WZ-11A	11P	20.00	24.00	15.50
WAFER-HY200WZ-12A	12P	22.00	26.00	15.50
WAFER-HY200WZ-13A	13P	24.00	28.00	15.50
WAFER-HY200WZ-14A	14P	26.00	30.00	15.50
WAFER-HY200WZ-15A	15P	28.00	32.00	15.50



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

序号	名称	材料	电镀 (锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
1	端子/Contact	黄铜	
2	基座/Wafer	LCP/PA66 (UL94V-0)	白色

UNLESS OTHERWISE SPECIFIED TOLERANCES



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

DECIMALS: ANGLES:
X :±0.20 X :±2°
X.X :±0.10 X.X :±1°
X.XX :±0.05

TITLE	WAFER HY 2.0MM 弯针 DIP TYPE		
DWN	xiong	PART NO. WAFER-HY200WZ-NA	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1

CUSTOMER COPY